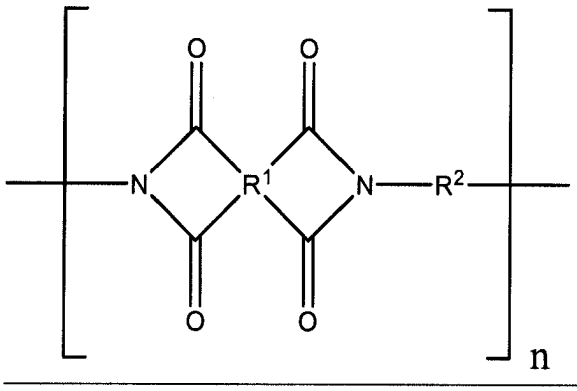
AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claim 1. (withdrawn/currently amended): A method for forming a surface graft, comprising the process of applying energy to the surface of a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV):

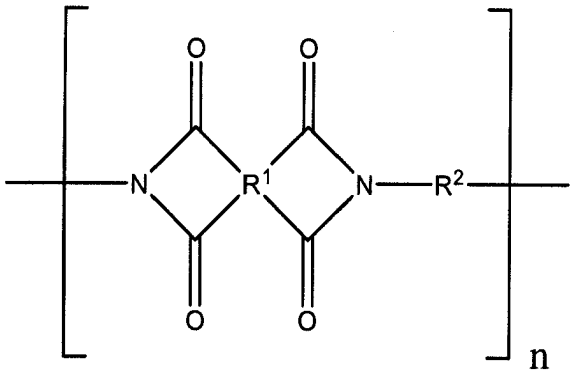


(IV),

wherein R^1 represents a tetravalent organic group, R^2 represents a divalent organic group, n represents an integer of 1 or more, and at least one of R^1 and R^2 is a group containing a structure having a polymerization initiating ability; to generate active points on the surface of the substrate and to generate a graft polymer that is directly bonded to the surface of the substrate starting from the active points and that has a polar group.

Claim 2. (withdrawn/currently amended): A method for forming a conductive film, comprising the processes of:

applying energy to the surface of a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV):



(IV),

wherein R^1 represents a tetravalent organic group, R^2 represents a divalent organic group, n represents an integer of 1 or more, and at least one of R^1 and R^2 is a group containing a structure having a polymerization initiating ability; to generate active points on the surface of the substrate and to generate a graft polymer that is directly bonded to the surface of the substrate starting from the active points and that has a polar group; and

causing a conductive material to adhere to the graft polymer.

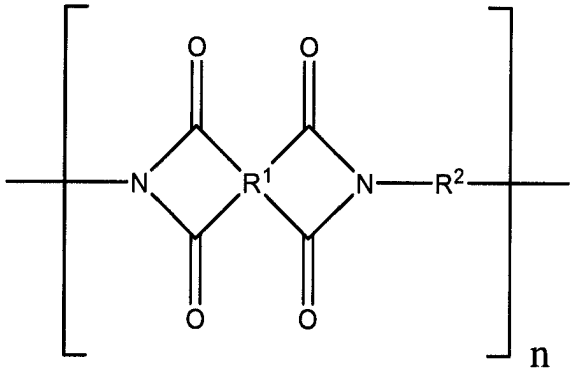
Claim 3. (withdrawn): The method for forming a conductive film of claim 2, further comprising the process of heating after the process of causing a conductive material to adhere to the graft polymer.

Claim 4. (withdrawn/currently amended): The method for forming a conductive film of claim 2, wherein the ~~conductive film is formed on both surfaces of~~ substrate has a film-like or

tabular shape ~~polyimide substrate having the polymerization initiating moiety in the skeleton thereof~~ and wherein the conductive film is formed on both surfaces of the substrate.

Claim 5. (withdrawn/currently amended): A method for forming a conductive film, comprising the processes of:

applying energy to the surface of a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV):



(IV),

wherein R^1 represents a tetravalent organic group, R^2 represents a divalent organic group, n represents an integer of 1 or more, and at least one of R^1 and R^2 is a group containing a structure having a polymerization initiating ability; to generate active points on the surface of the substrate and to generate a graft polymer that is directly bonded to the surface of the polyimide substrate starting from the active points and that has a polar group;

applying a metal ion or a metal salt to the graft polymer; and

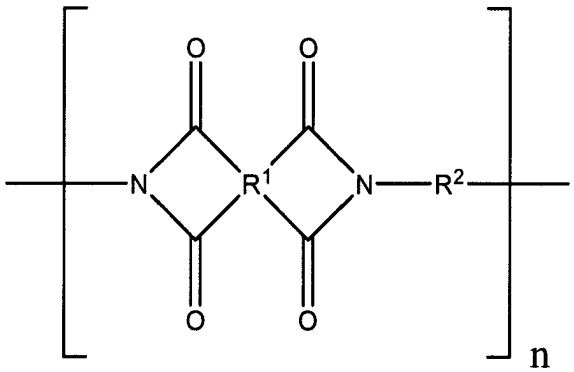
reducing the metal ion or a metal ion in the metal salt to deposit metal fine particles.

Claim 6. (withdrawn): The method for forming a conductive film of claim 5, further comprising the process of heating after the process of reducing the metal ion or the metal ion in the metal salt to deposit metal fine particles.

Claim 7. (withdrawn/currently amended): The method for forming a conductive film of claim 5, wherein the ~~conductive film is formed on both surfaces of~~ substrate has a film-like or tabular shape ~~polyimide substrate having the polymerization initiating moiety in the skeleton thereof~~ and wherein the conductive film is formed on both surfaces of the substrate.

Claim 8. (currently amended): A method for forming a conductive film, comprising the processes of:

applying energy to the surface of a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV):



(IV),

wherein R^1 represents a tetravalent organic group, R^2 represents a divalent organic group, n represents an integer of 1 or more, and at least one of R^1 and R^2 is a group containing a structure having a polymerization initiating ability;

to generate active points on the surface of the substrate; and to generate a graft polymer that is directly bonded to the surface of the substrate starting from the active points and that has a functional group interacting with an electroless plating catalyst or the precursor thereof;

applying the electroless plating catalyst or the precursor thereof to the graft polymer; and

carrying out electroless plating.

Claim 9. (original): The method for forming a conductive film of claim 8, further comprising the process of carrying out electroplating after the process of carrying out electroless plating.

Claim 10. (currently amended): The method for forming a conductive film of claim 8, wherein the ~~conductive film is formed on both surfaces of~~ substrate has a film-like or tabular shape ~~polyimide substrate having the polymerization initiating moiety in the skeleton thereof~~ and wherein the conductive film is formed on both surfaces of the substrate.

Claim 11. (withdrawn/currently amended): A surface graft material obtained by the method of claim 1, the material comprising:

a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV); and

a graft polymer directly bonded to the surface of the substrate.

Claim 12. (withdrawn/currently amended): A conductive material obtained by the method of claim 2, the material comprising:

a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV);

a graft polymer directly bonded to the surface of the substrate; and

a conductive material adhered to the graft polymer.

Claim 13. (withdrawn/currently amended): A conductive material obtained by the method of claim 5, the material comprising:

a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV);

a layer comprising a graft polymer directly bonded to the surface of the substrate; and

metal fine particles deposited in the layer by reducing the metal ion or a metal ion in a metal salt.

Claim 14. (currently amended): A conductive material obtained by the method of claim 8, the material comprising:

a substrate containing polyimide ~~having a polymerization initiating moiety in the skeleton thereof~~ represented by general formula (IV);

a layer comprising a graft polymer directly bonded to the surface of the substrate; and

metal fine particles deposited in the layer deposited by carrying out electroless plating.

Claim 15. (withdrawn): A method for forming a metal pattern, comprising the process of etching the conductive film obtained by the method for forming a conductive film of claim 2.

Claim 16. (withdrawn): A method for forming a metal pattern, comprising the process of etching the conductive film obtained by the method for forming a conductive film of claim 5.

Claim 17. (currently amended): A method for forming a conductive material having a metal pattern, wherein said method comprises the ~~comprising the~~ process of etching the conductive film obtained by the method for forming a conductive film of claim 8.

Claim 18. (withdrawn): A method for forming a multilayer wiring board which has, on a substrate, at least two metal layers that include the metal pattern obtained by the method for forming a metal pattern of claim 15 and an insulating layer disposed therebetween, comprising:

a drilling process of forming an opening in the insulating layer; and

a conductivity process of endowing conductivity to the opening, to connect at least two metal layers electrically.

Claim 19. (withdrawn): A method for forming a multilayer wiring board which has, on a substrate, at least two metal layers that include the metal pattern obtained by the method for forming a metal pattern of claim 16 and an insulating layer disposed therebetween, comprising:

a drilling process of forming an opening in the insulating layer; and

a conductivity process of endowing conductivity to the opening, to connect at least two metal layers electrically.

Claim 20. (currently amended): A method for forming a multilayer wiring board which has, on a substrate, at least two metal layers that include the conductive layer having said metal pattern obtained by the method for forming said conductive material as claimed in ~~metal pattern of~~ claim 17 and an insulating layer disposed therebetween, comprising:

a drilling process of forming an opening in the insulating layer; and

a conductivity process of endowing conductivity to the opening, to connect at least two metal layers electrically.

Claim 21. (new): The method for forming a surface graft of claim 1, wherein the energy is applied by ultraviolet light.

Claim 22. (new): The method for forming a conductive film of claim 2, wherein the energy is applied by ultraviolet light.

Claim 23. (new): The method for forming a conductive film of claim 5, wherein the energy is applied by ultraviolet light.

Claim 24. (new): The method for forming a conductive film of claim 8, wherein the energy is applied by ultraviolet light.